

Specification for Approval

Date: 2020/08/11

Customer : 深圳臺慶

TAI-TECH P/N: WCM1608F2SNF-121T04

CUSTOMER P/N: _____

DESCRIPTION: _____

QUANTITY: _____ pcs

REMARK:		
Customer Approval Feedback		

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Wire Wound Type Common Mode Filter

WCM1608F2SNF-121T04

ECN HISTORY LIST					
REV	DATE	DESCRIPTION	APPROVED	CHECKED	DRAWN
1.0	20/07/15	新發行	楊祥忠	林志鴻	何玉蓮
備 註					

Wire Wound Type Common Mode Filter

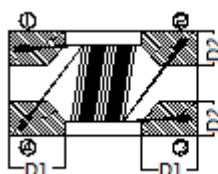
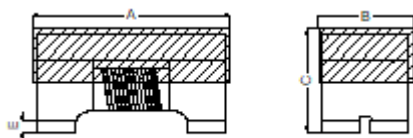
WCM1608F2SNF-121T04

1. Features

1. High common mode impedance at high frequency cause excellent noise suppression performance.
2. WCM1608F2SNF series realizes small size and low profile. 1.6x0.8x1.1 mm.
3. 100% Lead(Pb) & Halogen-Free and RoHS compliant.
4. Operating temperature-40~+125°C (Including self - temperature rise)



2. Dimension



Series	A(mm)	B(mm)	C(mm)	D1(mm)	D2(mm)	E(mm)
1608F2SNF	1.60±0.15	0.85±0.15	1.10±0.15	0.30Typ.	0.30Typ.	0.03 min.

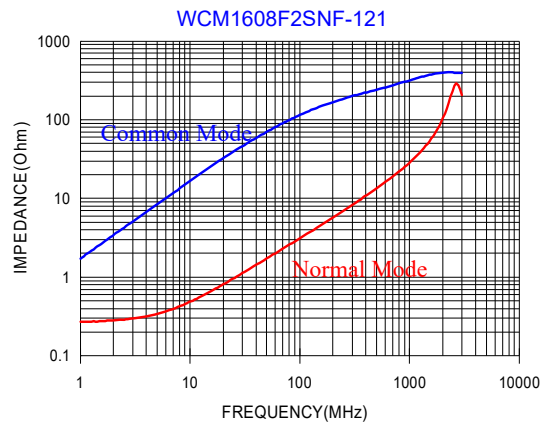
3. Part Numbering



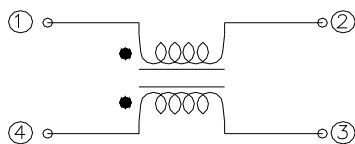
A: Series	
B: Dimension	
C: Material	Ferrite Core
D: Number of Lines	2=2 lines
E: Type	S=Shielded , N=Unshielded
F: Lead free	
G: Impedance	121=120Ω
H: Packaging	T=Taping and Reel
I: Rated Current	04=450mA

4. Specification

TAI-TECH Part Number	Common mode Impedance (Ω)	Test Frequency (MHz)	DC Resistance (Ω) max.	Rated Current (mA)max.	Rated Volt. (Vdc) max.	Withstand Volt. (Vdc) max.	IR (Ω) min.
WCM1608F2SNF-121T04	120±25%	100	0.175	450	50	125	10M

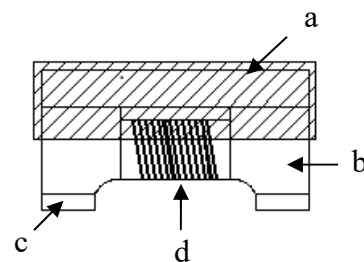


5. Schematic Diagram



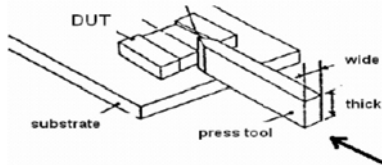
6. Materials

No.	Description	Specification
a.	Upper Plate	Ferrite & UV Glue
b.	Core	Ferrite Core
	Termination	Ag/Ni/Sn
d	Wire	Enameled Copper Wire



7. Reliability and Test Condition

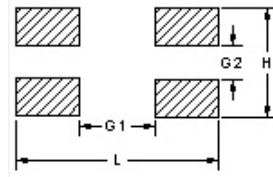
Item	Performance	Test Condition
Operating temperature	-40~+125°C (Including self - temperature rise)	
Storage temperature	-40~+125°C (on board)	
Electrical Performance Test		
Z(common mode)	Refer to standard electrical characteristics list.	Agilent-4291A+ Agilent -16197A
DCR		Agilent-4338B
I.R.		Agilent4339
Temperature Rise Test	Rated Current ΔT 40°C Max	1.Applied the allowed DC current. 2.Temperature measured by digital surface thermometer
Reliability Test		
Life Test	Appearance : No damage. Impedance : within±15% of initial value RDC : within ±15% of initial value and shall not exceed the specification value	Preconditioning: Run through IR reflow for 3 times.(IPC/JEDEC J-STD-020E Classification Reflow Profiles) Temperature : 125±2°C Applied current : rated current Duration : 1000±12hrs Measured at room temperature after placing for 24±2 hrs
Load Humidity		Preconditioning: Run through IR reflow for 3 times.(IPC/JEDEC J-STD-020E Classification Reflow Profiles) Humidity : 85±2% R.H, Temperature : 85°C±2°C Duration : 1000hrs Min. Bead : with 100% rated current · Inductance: with 10% rated current Measured at room temperature after placing for 24±2 hrs
Moisture Resistance		Preconditioning: Run through IR reflow for 3 times.(IPC/JEDEC J-STD-020E Classification Reflow Profiles 1. Baked at50°C for 25hrs, measured at room temperature after placing for 4 hrs. 2. Raise temperature to 65±2°C 90-100%RH in 2.5hrs, and keep 3 hours, cool down to 25°C in 2.5hrs. 3. Raise temperature to 65±2°C 90-100%RH in 2.5hrs, and keep 3 hours, cool down to 25°C in 2.5hrs,keep at 25°C for 2 hrs then keep at -10°C for 3 hrs 4. Keep at 25°C 80-100%RH for 15min and vibrate at the frequency of 10 to 55 Hz to 10 Hz, measure at room temperature after placing for 1~2 hrs.
Thermal shock		Preconditioning: Run through IR reflow for 3 times.(IPC/JEDEC J-STD-020E Classification Reflow Profiles Condition for 1 cycle Step1 : -40±2°C 30±5min Step2 : 25±2°C ≤0.5min Step3 : 125±2°C 30±5min Number of cycles : 500 Measured at room temperature after placing for 24±2 hrs
Vibration		Oscillation Frequency: 10Hz~2KHz~10Hz for 20 minute Equipment : Vibration checker Total Amplitude:10g Testing Time : 12 hours(20 minutes, 12 cycles each of 3 orientations) ·

Item	Performance	Test Condition															
Bending	Appearance : No damage. Impedance : within±15% of initial value	Shall be mounted on a FR4 substrate of the following dimensions: >=0805 inch(2012mm):40x100x1.2mm <0805 inch(2012mm):40x100x0.8mm Bending depth: >=0805 inch(2012mm):1.2mm <0805 inch(2012mm):0.8mm duration of 10 sec.															
Shock	RDC : within ±15% of initial value and shall not exceed the specification value	<table border="1"> <thead> <tr> <th>Type</th> <th>Peak value (g's)</th> <th>Normal duration (D) (ms)</th> <th>Wave form</th> <th>Velocity change (V)ft/sec</th> </tr> </thead> <tbody> <tr> <td>SMD</td> <td>50</td> <td>11</td> <td>Half-sine</td> <td>11.3</td> </tr> <tr> <td>Lead</td> <td>50</td> <td>11</td> <td>Half-sine</td> <td>11.3</td> </tr> </tbody> </table>	Type	Peak value (g's)	Normal duration (D) (ms)	Wave form	Velocity change (V)ft/sec	SMD	50	11	Half-sine	11.3	Lead	50	11	Half-sine	11.3
Type	Peak value (g's)	Normal duration (D) (ms)	Wave form	Velocity change (V)ft/sec													
SMD	50	11	Half-sine	11.3													
Lead	50	11	Half-sine	11.3													
Solder ability	More than 95% of the terminal electrode should be covered with solder.	a. Method B, 4 hrs @155°C dry heat @235°C±5°C Testing Time :5 +0/-0.5 seconds b. Method D category 3, (8hours ± 15 min)@ 260°C±5°C Testing Time :30 +0/-0.5 seconds															
Resistance to Soldering Heat		Depth: completely cover the termination <table border="1"> <thead> <tr> <th>Temperature(°C)</th> <th>Time(s)</th> <th>Temperature ramp/immersion and emersion rate</th> <th>Number of heat cycles</th> </tr> </thead> <tbody> <tr> <td>260 ±5 (solder temp)</td> <td>10 ±1</td> <td>25mm/s ±6 mm/s</td> <td>1</td> </tr> </tbody> </table>	Temperature(°C)	Time(s)	Temperature ramp/immersion and emersion rate	Number of heat cycles	260 ±5 (solder temp)	10 ±1	25mm/s ±6 mm/s	1							
Temperature(°C)	Time(s)	Temperature ramp/immersion and emersion rate	Number of heat cycles														
260 ±5 (solder temp)	10 ±1	25mm/s ±6 mm/s	1														
Terminal Strength	Appearance : No damage. Impedance : within±15% of initial value RDC : within ±15% of initial value and shall not exceed the specification value e	Preconditioning: Run through IR reflow for 3 times.(IPC/JEDEC J-STD-020E Classification Reflow Profiles With the component mounted on a PCB with the device to be tested, apply a force(>0805:1kg , <=0805:0.5kg)to the side of a device being tested. This force shall be applied for 60 +1 seconds. Also the force shall be applied gradually as not to apply a shock to the component being tested. 															

8. Soldering and Mounting

8-1. Recommended PC Board Pattern

	WCM1608F2SN
L(mm)	2.10
H(mm)	1.00
G1(mm)	0.70
G2(mm)	0.30



8-2. Soldering

Mildly activated rosin fluxes are preferred. TAI-TECH terminations are suitable for re-flow soldering systems. If hand soldering cannot be avoided, the preferred technique is the utilization of hot air soldering tools.

8-2.1 Soldering Reflow:

Recommended temperature profiles for lead free re-flow soldering in Figure 1. Table 1.1&1.2 (J-STD-020E)

8-2.2 Soldering Iron:

Products attachment with a soldering iron is discouraged due to the inherent process control limitations. In the event that a soldering iron must be employed the following precautions are recommended. (Figure 2.)

- Preheat circuit and products to 150°C
- Never contact the ceramic with the iron tip
- Use a 20 watt soldering iron with tip diameter of 1.0mm
- 350°C tip temperature (max)
- 1.0mm tip diameter (max)
- Limit soldering time to 4~5sec.

Fig.1 Soldering Reflow

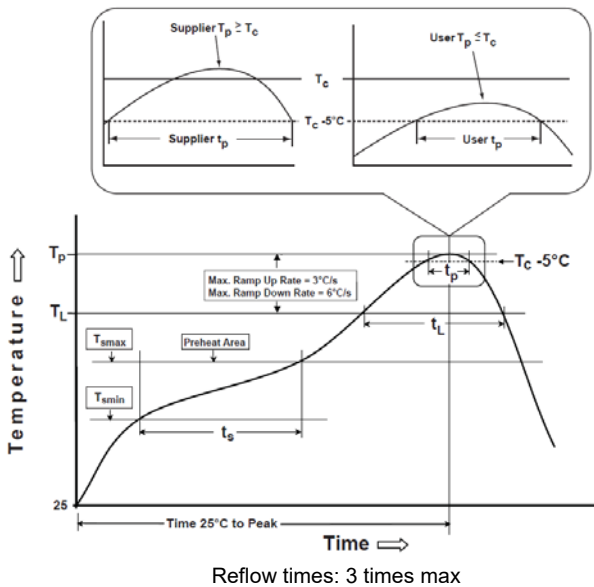


Fig.2 Iron Reflow

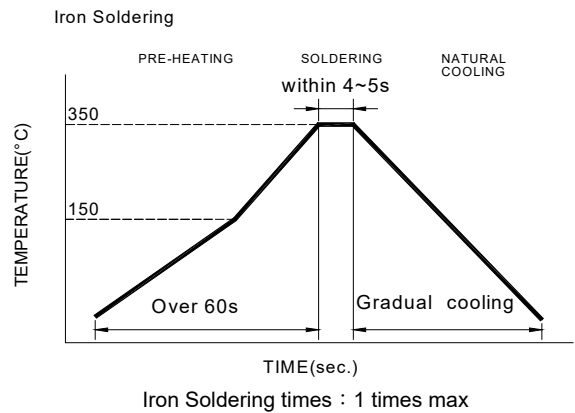


Table (1.1): Reflow Profiles

Profile Type:	Pb-Free Assembly
Preheat -Temperature Min(T_{smin}) -Temperature Max(T_{smax}) -Time(t_s)from(T_{smin} to T_{smax})	150°C 200°C 60-120seconds
Ramp-up rate(T_L to T_p)	3°C/second max.
Liquidus temperature(T_L) Time(t_L)maintained above T_L	217°C 60-150 seconds
Classification temperature(T_c)	See Table (1.2)
Time(t_p) at $T_c - 5^\circ\text{C}$ (T_p should be equal to or less than T_c .)	< 30 seconds
Ramp-down rate(T_p to T_L)	6°C /second max.
Time 25°C to peak temperature	8 minutes max.

T_p : maximum peak package body temperature, T_c : the classification temperature.

For user (customer) T_p should be equal to or less than T_c .

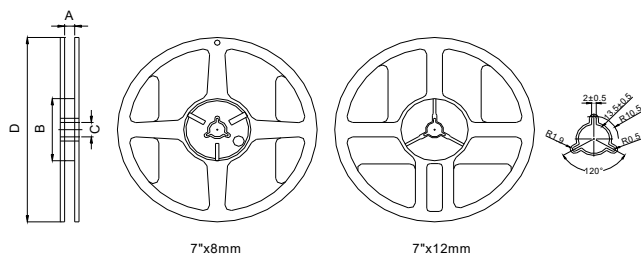
Table (1.2) Package Thickness/Volume and Classification Temperature (T_c)

	Package Thickness	Volume mm ³ <350	Volume mm ³ 350-2000	Volume mm ³ >2000
PB-Free Assembly	<1.6mm	260°C	260°C	260°C
	1.6-2.5mm	260°C	250°C	245°C
	≥2.5mm	250°C	245°C	245°C

Reflow is referred to standard IPC/JEDEC J-STD-020E ◦

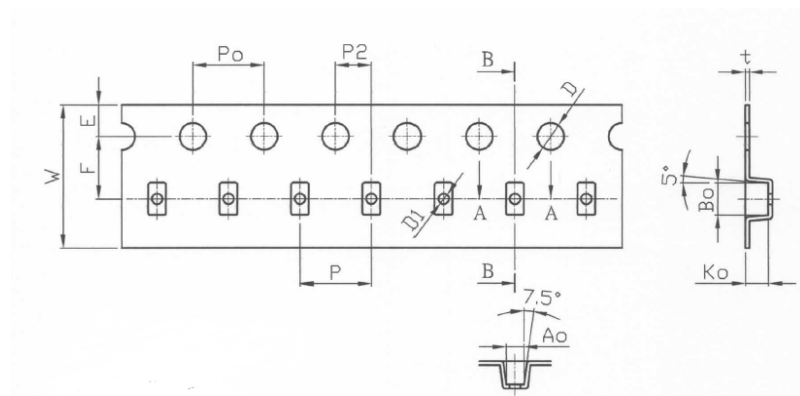
9. Packaging Information

9-1. Reel Dimension



Type	A(mm)	B(mm)	C(mm)	D(mm)
7"x8mm	9.0±0.5	60±2	13.5±0.5	178±2

9-2. Tape Dimension / 8mm

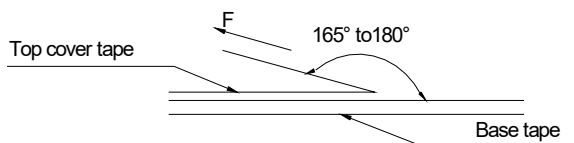


Series	W(mm)	P(mm)	E(mm)	F(mm)	P2(mm)	D(mm)	D1(mm)	P0(mm)	A0(mm)	B0(mm)	K0(mm)	t(mm)
WCM1608F2SN	8.00±0.10	4.00±0.10	1.75±0.10	3.50±0.05	2.00±0.05	1.50+0.10/-0.00	0.60±0.05	4.00±0.10	1.00±0.10	1.80±0.10	1.30±0.10	0.22±0.05

9-3. Packaging Quantity

Chip size	Chip/Reel	Inner Box	Middle Box	Carton
WCM1608F2SN	3000	15000	75000	150000

9-4. Tearing Off Force



The force for tearing off cover tape is 15 to 80 grams in the arrow direction under the following conditions.

Room Temp. (°C)	Room Humidity (%)	Room atm (hPa)	Tearing Speed mm/min
5~35	45~85	860~1060	300

Application Notice

- Storage Conditions(component level)
 - To maintain the solder ability of terminal electrodes:
 - TAI-TECH products meet IPC/JEDEC J-STD-020E standard-MSL, level 1.
 - Temperature and humidity conditions: Less than 40°C and 60% RH.
 - Recommended products should be used within 12 months from the time of delivery.
 - The packaging material should be kept where no chlorine or sulfur exists in the air.
- Transportation
 - Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
 - The use of tweezers or vacuum pick up is strongly recommended for individual components.
 - Bulk handling should ensure that abrasion and mechanical shock are minimized.

測試報告

Test Report

號碼(No.) : CE/2020/33003

日期(Date) : 2020/03/19

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西北臺慶科技股份有限公司 / TAI-TECH ADVANCED ELECTRONICS CO., LTD.

(臺慶精密電子(昆山)有限公司 / TAI-TECH ADVANCED ELECTRONICS (KUN-SHAN) CO., LTD.)

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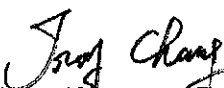
(江蘇省昆山市蓬朗昆嘉高科技工業區郭澤路 / GUO-ZE ROAD, KUNJIA HI-TECH INDUSTRIAL PARK, KUN-SHAN, JIANG-SU, CHINA)

(中國, 江蘇省, 宿遷市, 泗洪縣, 經濟開發區杭州路南側, 建設北路東側 / THE SOUTH HANGZHOU ROAD AND THE EAST JIANSHE ROAD, ECONOMIC DEVELOPMENT ZONE, SIHONG COUNTY, SUQIANCITY, JIANGSU PROVINCE, P, R, CHINA)

以下測試樣品係由申請廠商所提供及確認 (The following sample(s) was/were submitted and identified by/on behalf of the applicant as):

樣品名稱(Sample Description) : WIREWOUND SERIES
樣品型號(Style/Item No.) : WCM(YCW)、WCL、HSF、HDMI、DVI、BCM、PCM、TCM、LCM、LPF、TXF、ACM、DCM(YLW)、WIH、BPH、TNH、YCM、STF、APO、TLM、SWFS、QLL SERIES
收件日期(Sample Receiving Date) : 2020/03/12
測試期間(Testing Period) : 2020/03/12 to 2020/03/19

測試結果(Test Results) : 請參閱下一頁 (Please refer to following pages).


Troy Chang / Manager - Tech
Signed for and behalf of
SGS TAIWAN LTD.
Chemical Laboratory - Taipei



PIN CODE: C6A7457C

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(中國, 江蘇省, 宿遷市, 泗洪縣, 經濟開發區杭州路南側, 建設北路東側 / THE SOUTH HANGZHOU ROAD AND THE EAST JIANSHE ROAD, ECONOMIC DEVELOPMENT ZONE, SIHONG COUNTY, SUQIANCITY, JIANGSU PROVINCE, P, R, CHINA)

測試結果(Test Results)

測試部位(PART NAME)No. 1 : 整體混測 (MIXED ALL PARTS)

測試項目 (Test Items)	單位 (Unit)	測試方法 (Method)	MDL	結果 (Result)
				No. 1
鎘 / Cadmium (Cd)	mg/kg	參考IEC 62321-5 (2013), 以感應耦合電漿發射光譜儀檢測. / With reference to IEC 62321-5 (2013) and performed by ICP-OES.	2	n. d.
鉛 / Lead (Pb)	mg/kg		2	n. d.
汞 / Mercury (Hg)	mg/kg	參考IEC 62321-4:2013+ AMD1:2017, 以感應耦合電漿發射光譜儀檢測. / With reference to IEC 62321-4:2013+ AMD1:2017 and performed by ICP-OES.	2	n. d.
六價鉻 / Hexavalent Chromium Cr(VI)	mg/kg	參考IEC 62321-7-2 (2017), 以UV-VIS檢測. / With reference to IEC 62321-7-2 (2017) and performed by UV-VIS.	8	n. d.
多溴聯苯總和 / Sum of PBBs	mg/kg	參考IEC 62321-6 (2015), 以氣相層析/質譜儀檢測. / With reference to IEC 62321-6 (2015) and performed by GC/MS.	-	n. d.
一溴聯苯 / Monobromobiphenyl	mg/kg		5	n. d.
二溴聯苯 / Dibromobiphenyl	mg/kg		5	n. d.
三溴聯苯 / Tribromobiphenyl	mg/kg		5	n. d.
四溴聯苯 / Tetrabromobiphenyl	mg/kg		5	n. d.
五溴聯苯 / Pentabromobiphenyl	mg/kg		5	n. d.
六溴聯苯 / Hexabromobiphenyl	mg/kg		5	n. d.
七溴聯苯 / Heptabromobiphenyl	mg/kg		5	n. d.
八溴聯苯 / Octabromobiphenyl	mg/kg		5	n. d.
九溴聯苯 / Nonabromobiphenyl	mg/kg		5	n. d.
十溴聯苯 / Decabromobiphenyl	mg/kg	5	n. d.	

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測試項目 (Test Items)	單位 (Unit)	測試方法 (Method)	MDL	結果 (Result)
				No. 1
多溴聯苯醚總和 / Sum of PBDEs	mg/kg	參考IEC 62321-6 (2015), 以氣相層析/ 質譜儀檢測. / With reference to IEC 62321-6 (2015) and performed by GC/MS.	-	n. d.
一溴聯苯醚 / Monobromodiphenyl ether	mg/kg		5	n. d.
二溴聯苯醚 / Dibromodiphenyl ether	mg/kg		5	n. d.
三溴聯苯醚 / Tribromodiphenyl ether	mg/kg		5	n. d.
四溴聯苯醚 / Tetrabromodiphenyl ether	mg/kg		5	n. d.
五溴聯苯醚 / Pentabromodiphenyl ether	mg/kg		5	n. d.
六溴聯苯醚 / Hexabromodiphenyl ether	mg/kg		5	n. d.
七溴聯苯醚 / Heptabromodiphenyl ether	mg/kg		5	n. d.
八溴聯苯醚 / Octabromodiphenyl ether	mg/kg		5	n. d.
九溴聯苯醚 / Nonabromodiphenyl ether	mg/kg		5	n. d.
十溴聯苯醚 / Decabromodiphenyl ether	mg/kg	5	n. d.	
鹵素 / Halogen				
鹵素 (氟) / Halogen-Fluorine (F) (CAS No. : 14762-94-8)	mg/kg	參考BS EN 14582 (2016), 以離子層析儀 分析. / With reference to BS EN 14582 (2016). Analysis was performed by IC.	50	n. d.
鹵素 (氯) / Halogen-Chlorine (Cl) (CAS No. : 22537-15-1)	mg/kg		50	n. d.
鹵素 (溴) / Halogen-Bromine (Br) (CAS No. : 10097-32-2)	mg/kg		50	n. d.
鹵素 (碘) / Halogen-Iodine (I) (CAS No. : 14362-44-8)	mg/kg		50	n. d.
全氟辛烷磺酸 / Perfluorooctane sulfonates (PFOS-Acid, Metal Salt, Amide)	mg/kg	參考US EPA 3550C (2007), 以液相層析/ 質譜儀檢測. / With reference to US EPA 3550C (2007). Analysis was performed by LC/MS.	10	n. d.
全氟辛酸 / PFOA (CAS No. : 335-67-1)	mg/kg		10	n. d.

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測試項目 (Test Items)	單位 (Unit)	測試方法 (Method)	MDL	結果 (Result)
				No. 1
鄰苯二甲酸丁苯甲酯 / BBP (Butyl Benzyl phthalate) (CAS No. : 85-68-7)	mg/kg	參考IEC 62321-8 (2017), 以氣相層析/質譜儀檢測. / With reference to IEC 62321-8 (2017). Analysis was performed by GC/MS.	50	n. d.
鄰苯二甲酸二丁酯 / DBP (Dibutyl phthalate) (CAS No. : 84-74-2)	mg/kg		50	n. d.
鄰苯二甲酸二(2-乙基己基)酯 / DEHP (Di- (2-ethylhexyl) phthalate) (CAS No. : 117-81-7)	mg/kg		50	n. d.
鄰苯二甲酸二異丁酯 / DIBP (Di-isobutyl phthalate) (CAS No. : 84-69-5)	mg/kg		50	n. d.
鄰苯二甲酸二異癸酯 / DIDP (Di-isodecyl phthalate) (CAS No. : 26761-40-0; 68515-49-1)	mg/kg		50	n. d.
鄰苯二甲酸二異壬酯 / DINP (Di-isononyl phthalate) (CAS No. : 28553-12-0; 68515-48-0)	mg/kg		50	n. d.
鄰苯二甲酸二正辛酯 / DNOP (Di-n-octyl phthalate) (CAS No. : 117-84-0)	mg/kg		50	n. d.
鄰苯二甲酸二正己酯 / DNHP (Di-n-hexyl phthalate) (CAS No. : 84-75-3)	mg/kg		50	n. d.
鄰苯二甲酸二戊酯 / DNPP (Di-n-pentyl phthalate) (CAS No. : 131-18-0)	mg/kg		50	n. d.
六溴環十二烷及所有主要被辨別出的異構物 / Hexabromocyclododecane (HBCDD) and all major diastereoisomers identified (α - HBCDD, β - HBCDD, γ - HBCDD) (CAS No. : 25637-99-4 and 3194-55-6 (134237-51-7, 134237-50-6, 134237-52-8))	mg/kg	參考IEC 62321 (2008), 以氣相層析/質譜儀檢測. / With reference to IEC 62321 (2008). Analysis was performed by GC/MS.	5	n. d.

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測試項目 (Test Items)	單位 (Unit)	測試方法 (Method)	MDL	結果 (Result)
				No. 1
銻 / Antimony (Sb)	mg/kg	參考US EPA 3052 (1996), 以感應耦合電漿發射光譜儀檢測. / With reference to US EPA 3052 (1996). Analysis was performed by ICP-OES.	2	n. d.
鈹 / Beryllium (Be)	mg/kg	參考US EPA 3052 (1996), 以感應耦合電漿發射光譜儀檢測. / With reference to US EPA 3052 (1996). Analysis was performed by ICP-OES.	2	n. d.

備註(Note) :

1. mg/kg = ppm ; 0.1wt% = 1000ppm
2. MDL = Method Detection Limit (方法偵測極限值)
3. n. d. = Not Detected (未檢出)
4. "-" = Not Regulated (無規格值)
5. 樣品的測試是基於申請人要求混合測試, 報告中的混合測試結果不代表其中個別單一材質的含量. (The samples was/were analyzed on behalf of the applicant as mixing sample in one testing. The above results was/were only given as the informality value.)

PFOS參考資訊(Reference Information) : 持久性有機污染物 POPs - (EU) 2019/1021

PFOS濃度在物質或製備中不得超過0.001%(10ppm), 在半成品、成品或零部件中不得超過0.1%(1000ppm), 在紡織品或塗層材料中不得超過 $1\mu\text{g}/\text{m}^2$ 。

(Outlawing PFOS as substances or preparations in concentrations above 0.001% (10ppm), in semi-finished products or articles or parts at a level above 0.1%(1000ppm), in textiles or other coated materials above $1\mu\text{g}/\text{m}^2$.)

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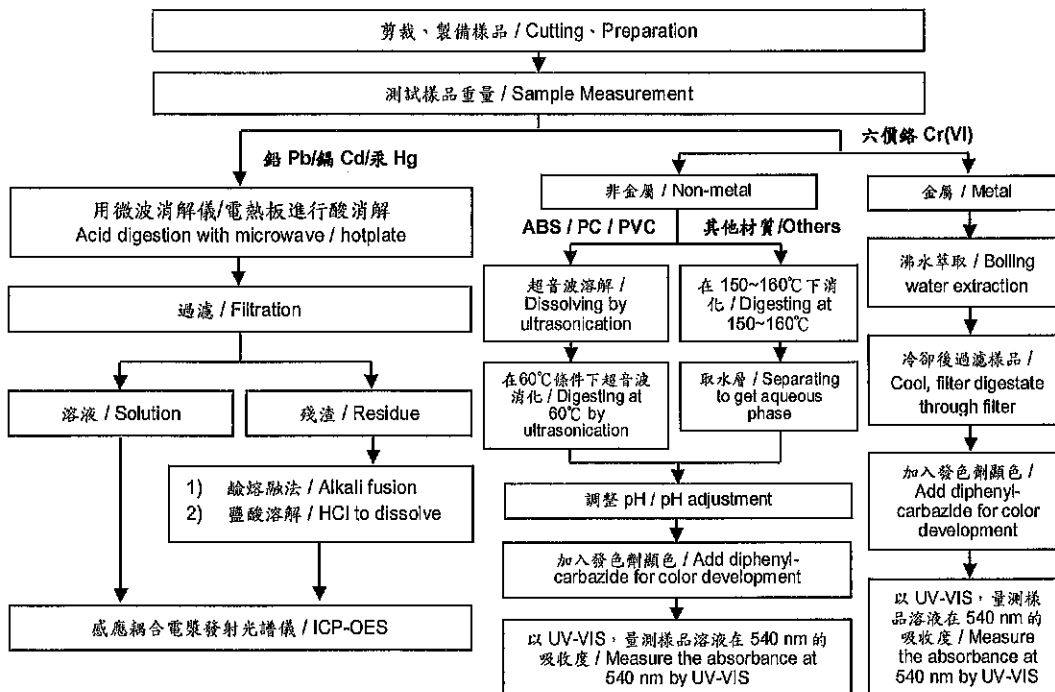
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重金屬流程圖 / Analytical flow chart of Heavy Metal

根據以下的流程圖之條件, 樣品已完全溶解。(六價鉻測試方法除外)

These samples were dissolved totally by pre-conditioning method according to below flow chart. (Cr⁶⁺ test method excluded)



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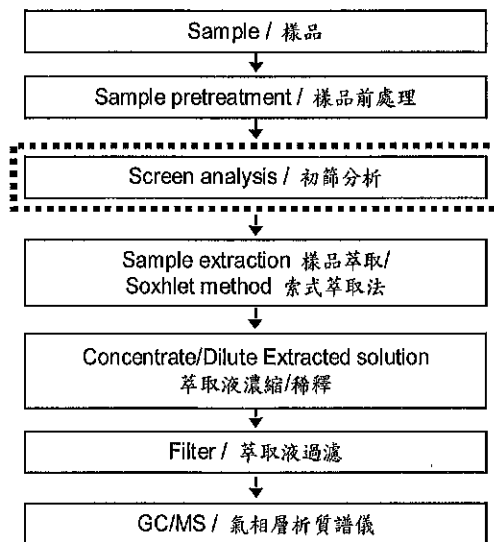
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多溴聯苯/多溴聯苯醚分析流程圖 / Analytical flow chart - PBB/PBDE

初次測試程序 / First testing process —————>

選擇性篩檢程序 / Optional screen process>

確認程序 / Confirmation process - - ->



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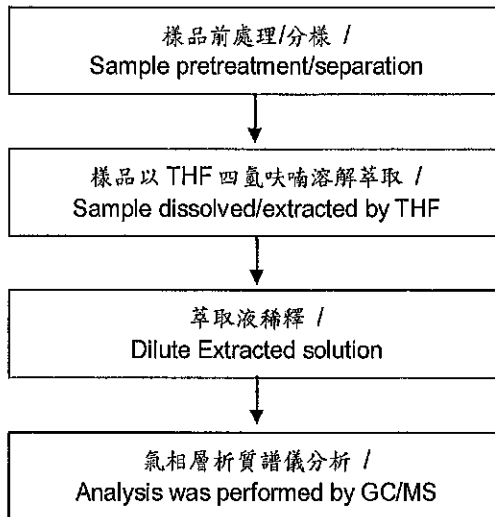
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可塑劑分析流程圖 / Analytical flow chart - Phthalate

【測試方法/Test method: IEC 62321-8】



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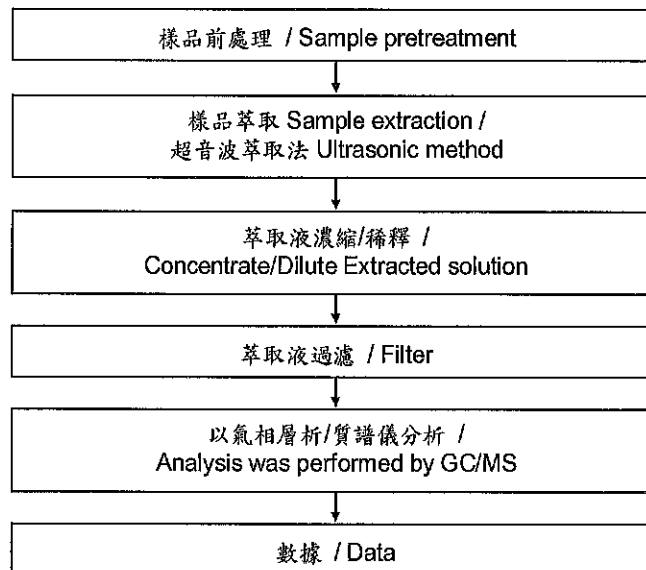
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六溴環十二烷分析流程圖 / Analytical flow chart - HBCDD



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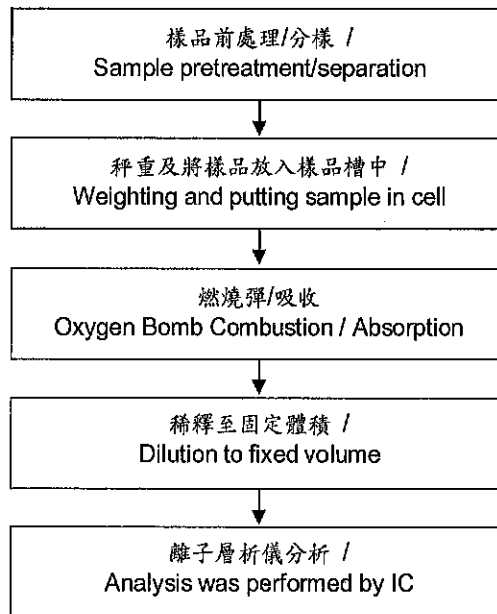
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鹵素分析流程圖 / Analytical flow chart - Halogen



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(臺慶精密電子(昆山)有限公司 / TAI-TECH ADVANCED ELECTRONICS (KUN-SHAN) CO., LTD.)

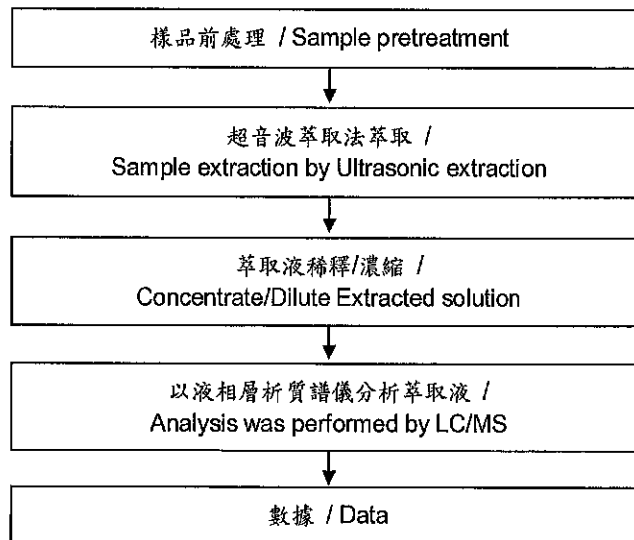
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全氟辛酸/全氟辛烷磺酸分析流程圖 / Analytical flow chart - PFOA/PFOS



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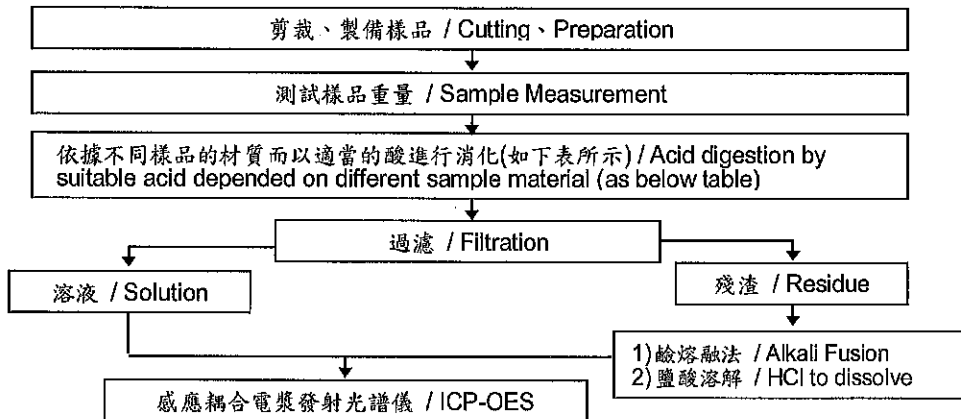
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元素以 ICP-OES 分析的消化流程圖 (Flow Chart of digestion for the elements analysis performed by ICP-OES)

根據以下的流程圖之條件, 樣品已完全溶解。 / These samples were dissolved totally by pre-conditioning method according to below flow chart.



鋼, 銅, 鋁, 焊錫 / Steel, copper, aluminum, solder	王水, 硝酸, 鹽酸, 氫氟酸, 雙氧水 / Aqua regia, HNO ₃ , HCl, HF, H ₂ O ₂
玻璃 / Glass	硝酸, 氫氟酸 / HNO ₃ /HF
金, 鉑, 鈱, 陶瓷 / Gold, platinum, palladium, ceramic	王水 / Aqua regia
銀 / Silver	硝酸 / HNO ₃
塑膠 / Plastic	硫酸, 雙氧水, 硝酸, 鹽酸 / H ₂ SO ₄ , H ₂ O ₂ , HNO ₃ , HCl
其他 / Others	加入適當的試劑至完全溶解 / Added appropriate reagent to total digestion

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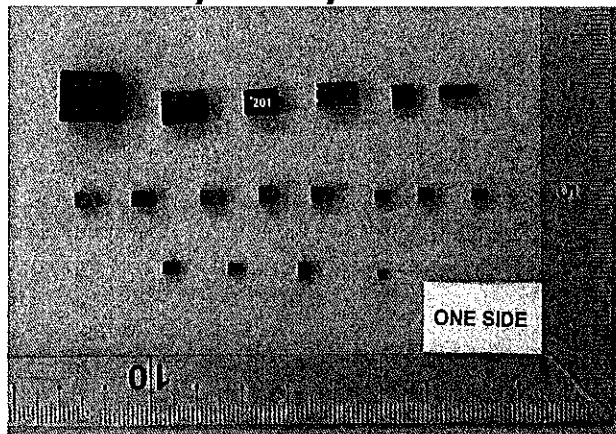
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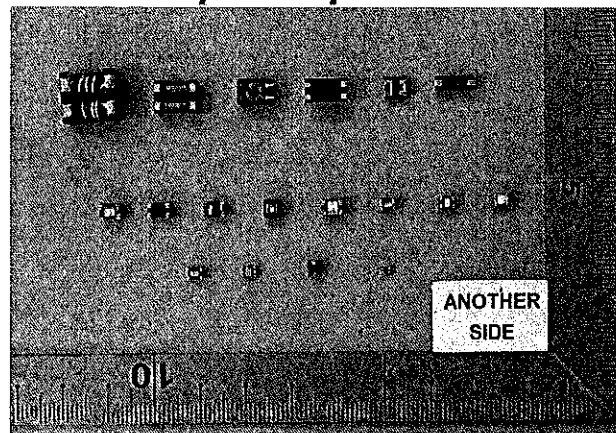
* 照片中如有箭頭標示, 則表示為實際檢測之樣品/部位. *

(The tested sample / part is marked by an arrow if it's shown on the photo.)

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** 報告結尾 (End of Report) **

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